

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IQE006NE2LM5	**Issued**	08. April 2022
MA#	MA005710435		
Package	PG-TSON-8-4	**Weight***	43.38 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.896	2.07	2.07	20664	20664
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		76	
	non noble metal	zinc	7440-66-6	0.013	0.03		305	
	non noble metal	iron	7439-89-6	0.265	0.61		6098	
	non noble metal	copper	7440-50-8	10.743	24.76	25.41	247621	254100
encapsulation	organic material	carbon black	1333-86-4	0.029	0.07		667	
	plastics	epoxy resin	-	1.491	3.44		34359	
	inorganic material	silicondioxide	60676-86-0	12.953	29.86	33.37	298560	333586
leadfinish	non noble metal	tin	7440-31-5	0.481	1.11	1.11	11089	11089
plating	noble metal	silver	7440-22-4	0.298	0.69	0.69	6870	6870
solder	noble metal	silver	7440-22-4	0.032	0.07		729	
	non noble metal	tin	7440-31-5	0.063	0.15		1458	
	non noble metal	lead	7439-92-1	1.171	2.70	2.92	26981	29168
heat sink clip	inorganic material	phosphorus	7723-14-0	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.015	0.03		339	
	non noble metal	copper	7440-50-8	14.697	33.86	33.90	338776	339217
clip attach	non noble metal	tin	7440-31-5	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.006	0.01		133	
	non noble metal	lead	7439-92-1	0.220	0.51	0.53	5067	5306
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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